

 UI Science Profile
Equipment for next generation

UI SCIENCE Co.,ltd.

Profile of UI SCIENCE

○Head office UI SCIENCE Co., Ltd.

○Address 187-1 Nanakoudai, Noda City, Chiba Prefecture, 278-0051,
Japan

TEL 04-7137-7383 FAX 04-7137-7384

○Company Profile

Established

September 2016

Capital

100,000,000Jpy

Main bank

Chiba bank、Keiyo bank、MSBC

Representative

President: CEO

Shinichi Umemoto

○Sales equipment type

RtoR Connector Plating Equipment

Full Auto Wafer Plating System

Semi Auto Wafer Plating System

Lead frame Plating Equipment Cut Sheet or RtoR

PCB Plating Equipment、

Plating Tool (Silicon mask etc)



Introduction of UI SCIENCE

Confidential

Concept of Equipment

- **We are familiar with the latest plating equipment technology.
State-of-the-art equipment group.**
- **Our equipment was designed for high spec ideas.
This is a custom-made Equipment for which you can request specifications.**

Organizational Structure

Officer Sales

Accounting, general affairs

Technical design

Production control

Production

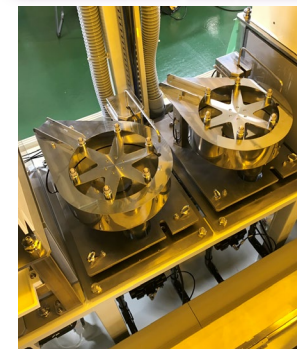
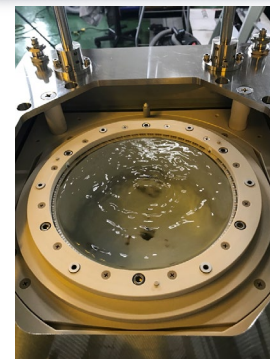
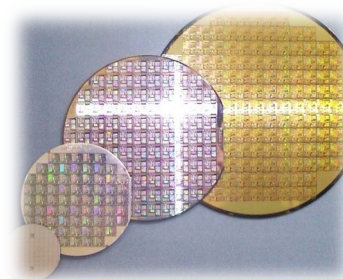
System Control

Introduction of Plating equipment.

Confidential

Full Auto Wafer Plating System

Model	: FAWPS-04~08
Chamber	: 4~8 Chamber
Through put	: MAX 10000wafer/month
Wafer size	: $\phi 75$ – $\phi 100$ – $\phi 125$ – $\phi 150$ – $\phi 200$ 3inch–4inch–5inch–6inch–8inch
Plating spec	: Cu、NI、Au、Sn etc
Wafer material	: Silicon Wafer /GaAs Wafer GaN Wafer etc



○Concept of system

- Equipped with SCARA robot for stable transportation and high quality plating .
- The two-handed SCARA robot does not stain the wafer.
- Production recipe, production record, production recording function installed (compliant with SECS standard)
- High quality plating supported by original face down Chamk
- Supports high-quality plating by installing wafer contact ring cleaning function



(Model 2023 $\phi 200$ –8chamber–4SRD)

Introduction of Plating equipment.

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Semi Auto Wafer Plating System

Model	: SAWPS-04~14
Chamber	: 4~14 Chamber
Through put	: MAX 10000wafer/month
Wafer size	: $\phi 75$ – $\phi 100$ – $\phi 125$ – $\phi 150$ – $\phi 200$ 3inch–4inch–5inch–6inch–8inch
Plating spec	: Cu、NI、Au、Sn etc
Wafer material	: Silicon Wafer /GaAs Wafer GaN Wafer etc

$\Phi 200$ 8inch Cu 4+4+2



$\Phi 200$ 8inch Cu 8+6



Introduction of Plating equipment.

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RtoR Connector Plating Equipment

Model : UIRC-01 ~04

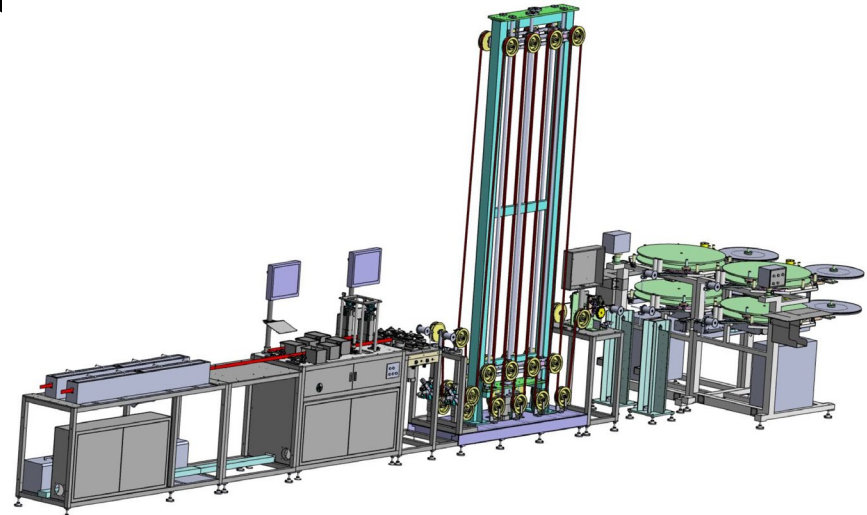
Number of line : 1line~4line (MAX4line)

Drive speed : 1.0~25.0m/min

Production item : Connector、Foap
: Thickness $t0.06 \sim t1.0\text{mm}$
: Hight 5~120mm

Basic plating spec : Ni+Pd+Au+Sn
: Cu+Sn+Reflow etc

Material : Cu、SUS etc



○Concept of Equipment

- narrow-pitch micro connector products and high quality plating support
- Automotive connector products and high quality plating support
- High-precision partial plating is possible by processing various parts plating tool



Introduction of Plating equipment.

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Lead frame Plating Equipment

RtoR type plating equipment

Model : UIRLF-02 ~04

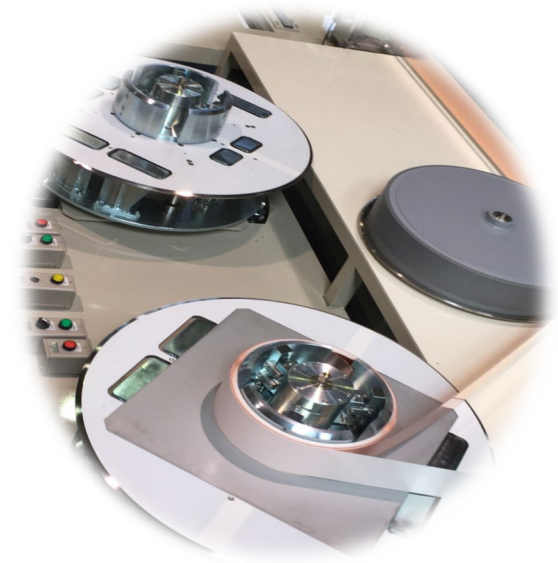
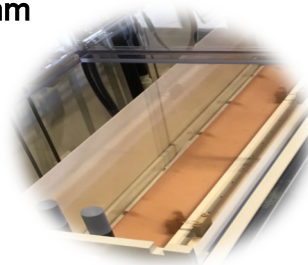
Number of line : 1line~4line (MAX4line)

Drive speed : 1.0~5.0m/min

Production item : Lead frame、Foap
: Thickness t0.06~t1.0mm
: Hight 5~120mm

Basic plating spec :Ni+Pd+Au
: Cu+Ag etc

Material : Cu、SUS etc



○Concept of Equipment

- High-precision partial plating is possible by processing various parts plating tool
- Spot plating position accuracy ± 0.07 mm achieved

Introduction of Plating equipment.

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Lead frame Plating Equipment

Cut sheet type plating equipment

Model : UICLF-02 ~04

Number of line : 1line~4line (MAX4line)

Conveyer speed : 1.0~2.0m/min

Production item : Lead frame cut sheet
: Thickness t0.06~t0.8mm
: Wide 50~100mm

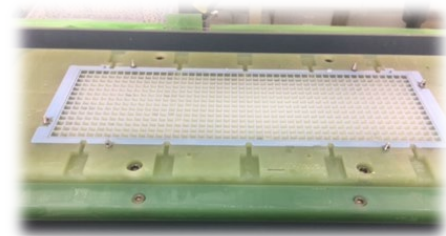
Basic plating spec :Ni+Pd+Au
: Cu+Ag etc

Material : Cu , SUS etc



○Concept of Equipment

- High-precision partial plating is possible by processing various parts plating tool
- Spot plating position accuracy ± 0.05 mm achieved



Introduction of control system (A D L S)

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Auto Data Logging System

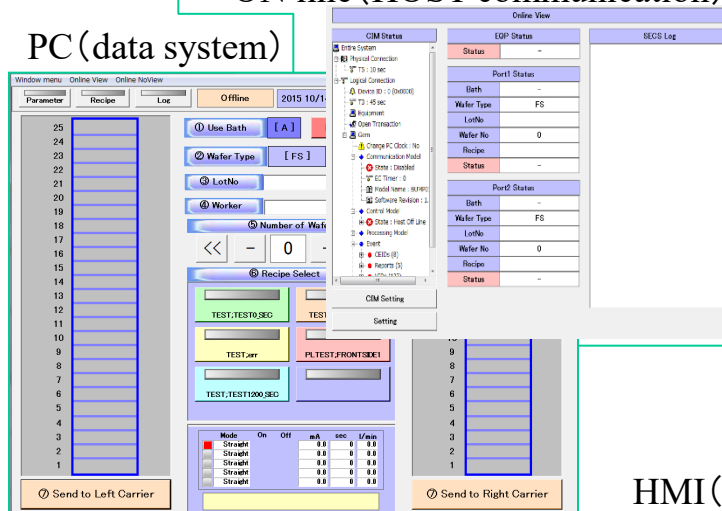
- Equipment control (Drive, robot control, etc.)
- Recipe D/L, data collection, alarm history management (PC control)
- Recipe U/L, host communication management (online control)



User HOST server
SECS/GEM

ON line (HOST communication)

PC (data system)



PLC (system Control)



PLC (system Control)



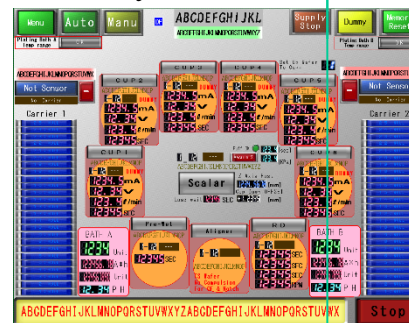
Melsecnet/H

M/C Control

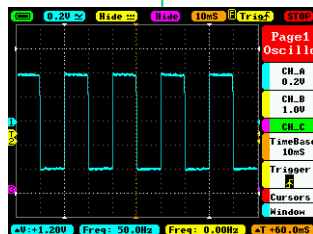
Ethernet

CC-Link
FAcom

HMI (system Control)



Ethernet



Current control board control, jet control, etc.

RS-232C communication

Ethernet

Inspection Control

In line record

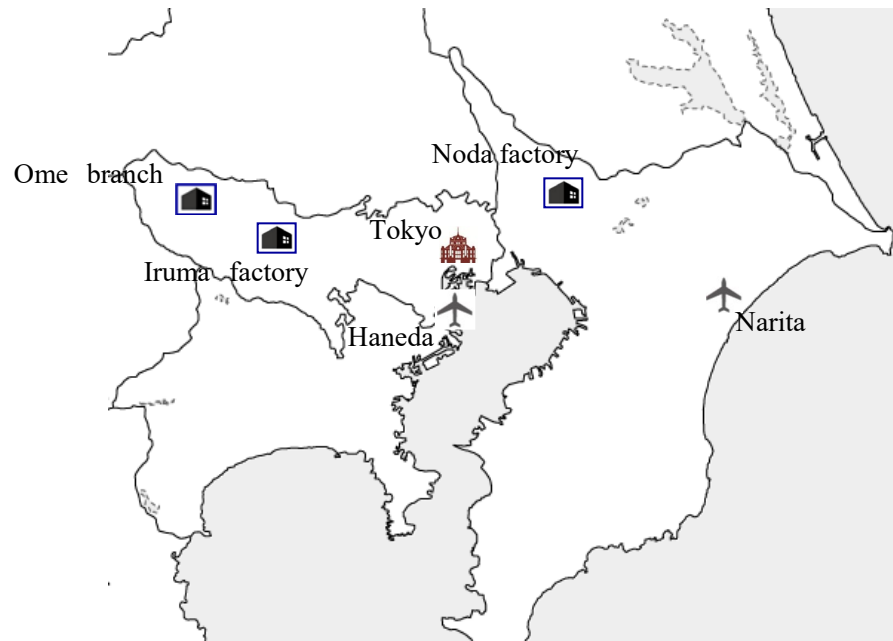


Access to UI SCIENCE

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Always access to the station

35 minutes by train from Tokyo Station
60 minutes by train from Haneda Airport
75 minutes by bus
60 minutes by train from Narita Airport
90 minutes by bus



Head office & Noda factory
Semiconductor Iruma factory
Tokyo branch

